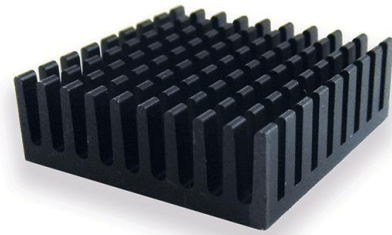


Product Data Sheet Type: PG3030/10/SE/SF

Group: HEATSINKS Board Level

For single mounting

Width :	30 mm
Height :	10 mm
Length :	30 mm
Minimum thermal resistance :	9,6 K/W
For device :	PGA BGA IC
Device mounted by :	Bonding
Heatsink mounted by :	Adhesive Bounding
Surface :	Black Anodised
Material :	AlMgSi0,5



- Heatsinks for microprocessors (Extrusion Technology)
- Direct mounting with self-adhesive foil
- Best possible heat radiation from black anodized surface
- RthKvalues apply to natural convection (without external ventilation)
- Arrangement and number of pins for optimal air flow
- Even heat distribution in the base and the pins in the direction of heat flow
- Suitable for forced and free convection
- Aluminium alloy Al MgSi 0.5
- Thermal conductivity: 180-200 W / mK
- Other dimensions and surface finishes by request

